



SOT666

plastic, surface-mounted package; 6 terminals; 1 mm pitch;
1.6 mm x 1.2 mm x 1.55 mm body

9 January 2017

Package information

1. Package summary

Dimensions (mm)	1.6 x 1.2 x 0.55
Terminal position code	D (double)
Package type descriptive code	SOT666
Package outline version code	SOT666
Manufacturer package code	SOT666
Package type industry code	SOT666
Package outline version description	plastic, surface-mounted package; 6 terminals; 1 mm pitch; 1.6 mm x 1.2 mm x 1.55 mm body
Package style descriptive code	SOT (small outline transistor)
Package body material type	P
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	SC18_1999_CHAPTER_5_2
Mounting method type	S (surface mount)
Generic mounting and soldering information	AN10365_3
Reflow soldering footprint	SOT666_fr
Package life cycle status	REL
Major version date	18-9-2008
Minor version date	14-5-2012
Security status	COMPANY PUBLIC
Modified date	26-10-2012
Issue date	16-3-2006
Web publication date	28-11-2012
Initial web publication date	18-1-2011
Customer specific indicator	N
Maturity	Product
Package author	Nair Deepa
Package approver	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	0.5	-	0.55	0.6	mm
D	package length	1.5	-	1.6	1.7	mm
E	package width	1.1	-	1.2	1.3	mm
e	nominal pitch	-	-	1	-	mm



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Symbol	Parameter		Min	Typ	Nom	Max	Unit
n ₂	actual quantity of termination		-	-	6	-	

2. Package outline

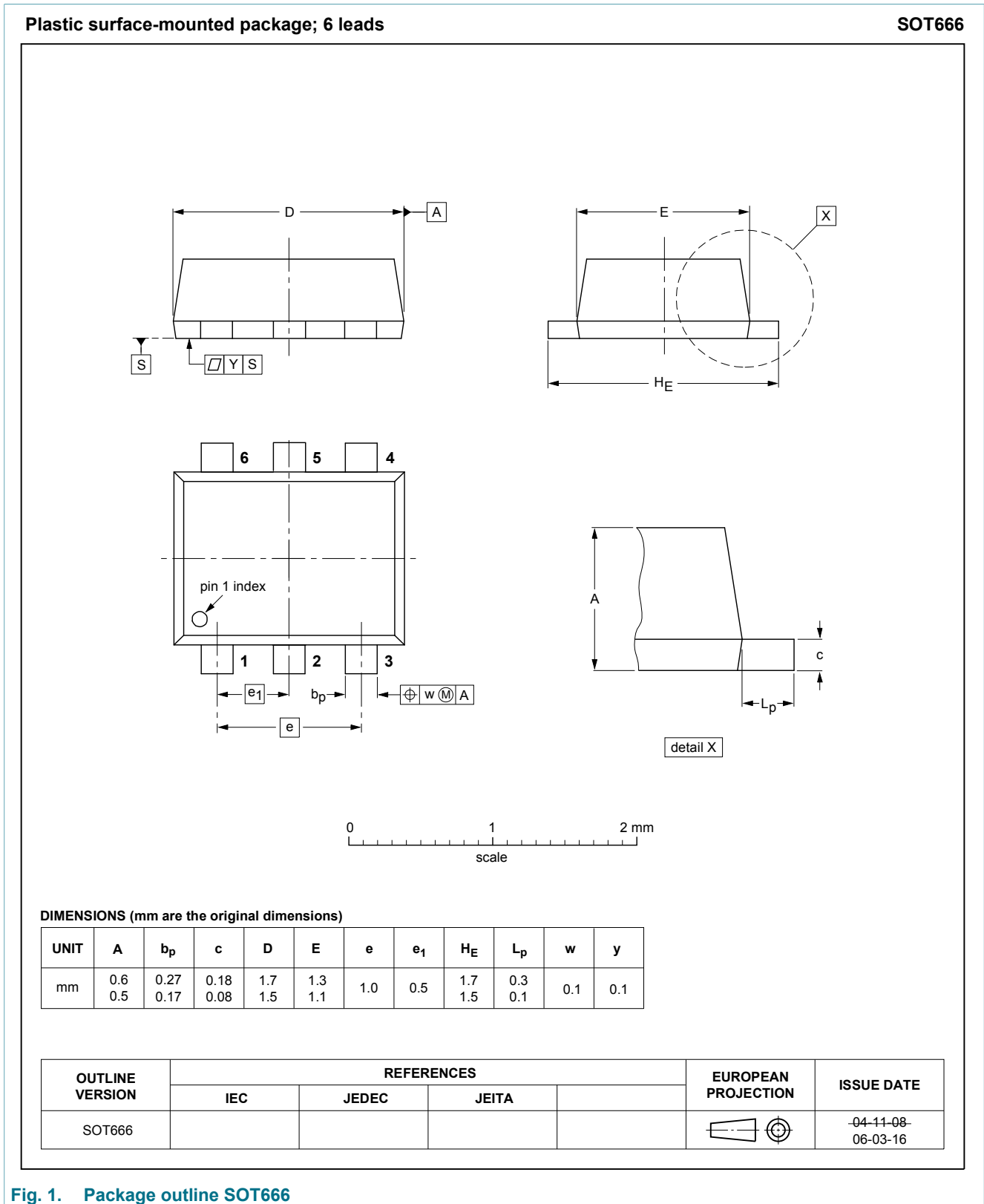


Fig. 1. Package outline SOT666

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3. Soldering

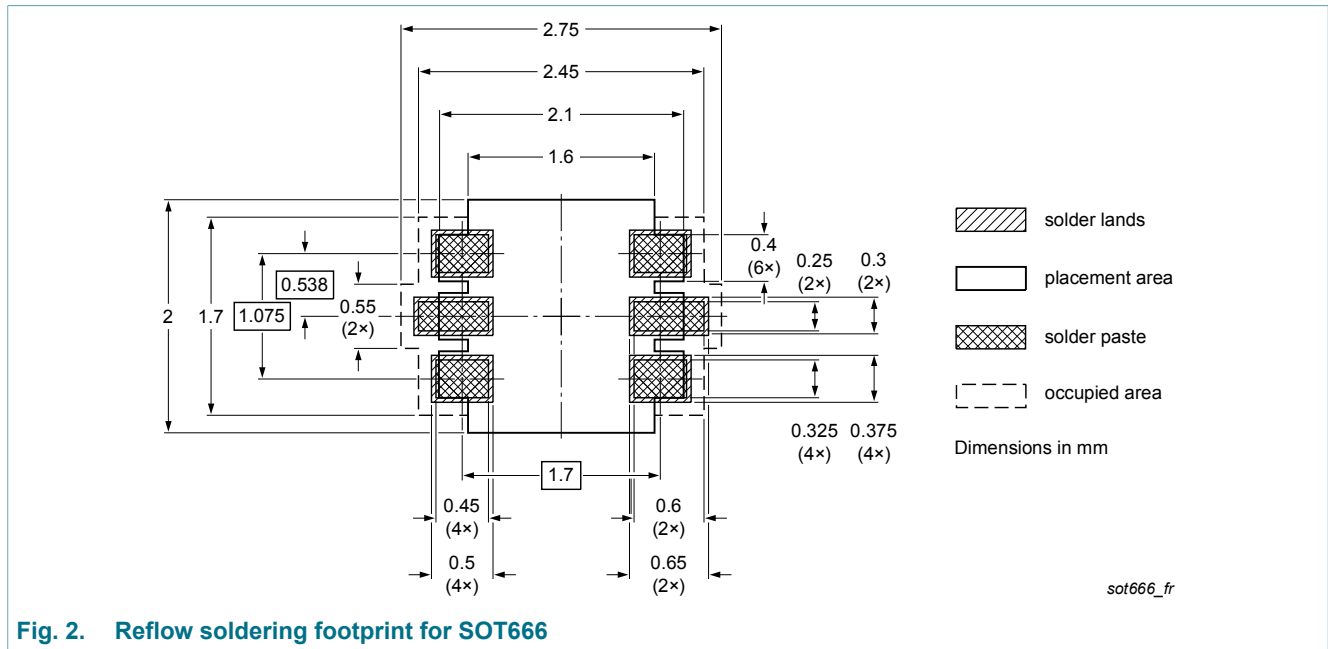


Fig. 2. Reflow soldering footprint for SOT666

4. Legal information

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Date of release: 9 January 2017
